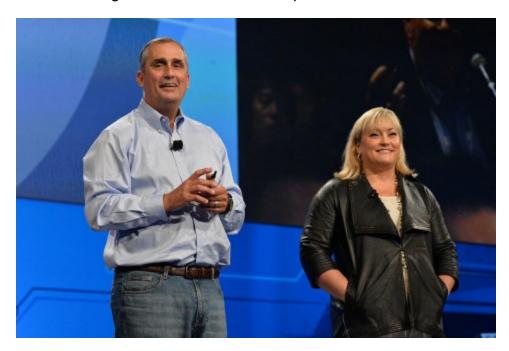September 9, 2014

ADDING MULTIMEDIA Intel Unveils New Developer Tools, Future Technologies Spanning Tablets, Analytics, Wearable Devices and PCs at Developer Forum

Announces Availability of Intel® Edison and 2nd Generation LTE Modem Platforms

SAN FRANCISCO--(BUSINESS WIRE)-- INTEL DEVELOPER FORUM -– Intel Corporation CEO Brian Krzanich kicked off Intel's annual technical conference with a broad set of computing initiatives and projects showing how the company is moving quickly to enable new market segments where everything is smart and connected. Krzanich and other executives announced new hardware and software developer tools, previewed upcoming Intel technologies and announced new products across several technology segments.

Intel CEO Brian Krzanich and President Renee James take questions from the IDF14 audience (Photo: Business Wire)

"With our diverse product portfolio and developer tools that span key growth segments, operating systems and form factors, Intel offers hardware and software developers new ways to grow as well as design flexibility," said Brian Krzanich, Intel CEO. "If it's smart and connected, it is best with Intel."

During the keynote, Krzanich was joined on the keynote stage by several Intel executives, Michael Dell, chairman and CEO of Dell*, and Greg McKelvey, executive vice president and chief strategy and marketing officer of the Fossil Group*.

The technical conference's format and content were revamped this year to appeal to an expanded range of engineers and programmers, reflecting Intel's efforts to extend the reach of Intel technology. The agenda and technology showcase content expanded beyond PCs,

mobile and the data center to also include the Internet of Things (IoT) and wearables and other new devices created by so-called "makers" and inventors. More than 4,500 people are attending the forum this week from around the world.

Developer Tools News Items

- Intel announced the Intel Reference Design for Android program to offer tablet users a high-quality, consistent experience based on the latest Android* operating system. Intel will help scale the deployment process of Android for tablet manufacturers by providing the software engineering work, streamlined access to Google Mobile Services*, as well as support for updates and upgrades to future Android releases.

- Intel announced the Analytics for Wearables (A-Wear) developer program that will accelerate development and deployment of new wearable applications with data-driven intelligence. The developer program integrates a number of software components, including tools and algorithms from Intel and data management capabilities from Cloudera* CDH all deployed on a cloud infrastructure optimized on Intel® architecture. Developers of Intel wearables will use the A-Wear developer program free of charge.

Intel Product Availability News Items

- Intel announced the first commercial availability of the Intel® XMM™ 7260 modem, now shipping in the Samsung* Galaxy Alpha smartphone for Europe and other regional markets. The Intel XMM 7260 and Intel® XMM™ 7262 modems support one of the industry's fastest mobile standards, delivering Category 6 data rates up to 300 Mbps. The modems are Intel's second-generation LTE platforms and provide device manufacturers a high-performance, power-efficient solution for the coming wave of LTE-Advanced networks and devices.

- Intel® Edison, a postage stamp-size computer with built-in wireless that was announced at CES, is now shipping and available. The platform is designed to enable rapid innovation and product development from inventors, entrepreneurs and consumer product designers by simplifying the design process, increasing durability and providing additional cost savings.

- AT&T* will be the exclusive carrier for the "My Intelligent Communication Accessory" (MICA) bracelet designed by Opening Ceremony, engineered by Intel, that was introduced last week in New York.

Product and Innovation Preview News Items

- Michael Dell and Krzanich previewed an upcoming Dell tablet with first-of-its-kind photo capabilities. The new Dell Venue 8 7000 Series with Intel® RealSense™ snapshot is the world's thinnest tablet and will be available in time for the holiday season. Intel RealSense snapshot is an enhanced photography solution that creates a high-definition depth map to enable measurement, refocus and selective filters with a touch of a finger. It will introduce new capabilities and new ways of using the tablet, opening up a new creative horizon for developers to come up with apps that change how consumers engage with their photos.

- Intel® Wireless Gigabit Docking – a full wireless experience that includes wireless

docking, wireless display and wireless charging – was demonstrated via an Intel reference design based on a 14nm next-generation Intel processor.

- Developers got a preview of the next generation 14nm Intel® Core™ processor for 2015.

- Renowned physicist Stephen Hawking joined the conference via video to discuss how technology for the disabled is often a proving ground for the technology of the future. In connection with Hawking's video attendance, Intel revealed for the first time a unique Connected Wheelchair Project, a proof of concept designed by Intel interns as part of the Intel Collaborators program. The project demonstrated how to transform standard "things" into data-driven, connected machines using the Intel Galileo Development Kit, based on Intel® Quark processors, and Intel® Gateway Solutions for the IoT, featuring Wind River* and McAfee* security products.

IDF Preview

- Developers will experience 164 technical sessions with industry and Intel experts.

- Intel's business units and more than 180 leading companies from around the world will showcase 700 hands-on demonstrations of their newest innovations and future technologies at the IDF Industry Technology Showcase.

- During the IoT mega session this morning, Intel Vice President Doug Davis will address interoperability and security challenges and describe Intel's integrated hardware and software building blocks for edge-to-cloud IoT solutions. He will disclose that Intel is collaborating with AT&T*, Cisco*, GE* and IBM* to create complete solutions utilizing their platforms and Intel's building blocks. The companies will announce joint products that are available today in addition to future product plans.

- In the Intel Edison, Wearables and New Devices mega session this afternoon, Intel Vice President Mike Bell will preview several Intel Edison-powered prototype devices, including a 3-D printed interactive garment and a braille printer and embosser. Meridian Audio*, a top high-performance audio and video component manufacturer, will also discuss how Intel Edison contributes to advancing its wireless audio product offerings.

- During the Software Developer mega session this afternoon, Intel Vice President Doug Fisher will introduce tools that help developers create software easier, faster and across ecosystems. He will also talk about the ease with which OEMs and ODMs will be able to build a Windows-* or Android-based device using customized tools and reference designs from Intel.

- In the Mobile Technology mega session this afternoon, Intel Vice President Hermann Eul will challenge developers to play a role in solving the world's most critical problems and advancing societies across the globe, in particular in developing countries, through innovations for the most prominent technology in people's hands, the mobile device. He will highlight the hardware, software and communications technologies that will allow developers to tap into this opportunity and aid in providing change, progress and innovation.

- During the Data Center mega session tomorrow morning, Intel Senior Vice President Diane Bryant will discuss how data centers are being re-architected, driven in large

part by the rise of the digital service economy. This session will include an update on future Intel silicon photonics products and details on how Intel is tailoring products for individual data center customers.

- In the PC Reinvention and Innovation mega session tomorrow morning, Intel Senior Vice President Kirk Skaugen will discuss how developers can address the 600 million unit global opportunity of 4-year-old and older PCs that could be replaced with exciting new form factors and new experiences across multiple operating systems. Skaugen will update developers on ChromeOS* and Intel® Wireless Display momentum, and as well as the Alliance for Wireless Power wireless charging consortium.

Supporting Resources

- Photos: MICA, "My Intelligent Communication Accessory", by Opening Ceremony and Intel
- Photo: Intel® Edison
- Photo: Dell Venue 8 7000 Series* with Intel RealSense Snapshot
- Fact sheet: Intel's 2014 LTE-Advanced Communications Platform Now Shipping
- Blog by Intel Vice President Doug Fisher: Intel Reference Design for Android
- Blog by Intel Vice President Mike Bell: Intel, Fossil to Advance Wearable Designs
- IDF14 keynote webcast
- IDF14 virtual media kit

About Intel

Intel (NASDAQ:INTC) is a world leader in computing innovation. The company designs and builds the essential technologies that serve as the foundation for the world's computing devices. As a leader in corporate responsibility and sustainability, Intel also manufactures the world's first commercially available "conflict-free" microprocessors. Additional information about Intel is available at newsroom.intel.com and blogs.intel.com, and about Intel's conflict-free efforts at conflictfree.intel.com.

Intel, Intel Core, Intel RealSense, XMM, Quark and the Intel logo are trademarks of Intel Corporation in the United States and other countries.
*Other names and brands may be claimed as the property of others.

Photos/Multimedia Gallery Available:
http://www.businesswire.com/multimedia/home/20140909006260/en/

Intel
Laura Anderson, 480-552-9020
Laura.m.anderson@intel.com

Source: Intel Corporation